



Special Issue of the



Journal of Ambient Intelligence and Humanized Computing

“Intelligent Computing and System towards Smart Manufacturing”

Description

With the integration and extensive applications of the new generation of information technologies (such as cloud computing, internet of things, big data, mobile internet, artificial intelligence) in manufacturing industry, a number of countries have put forward their national advanced manufacturing development strategies, such as Industry 4.0 in Germany, Industrial Internet and manufacturing system based on CPS (Cyber-Physical Systems) in the USA, as well as Made in China 2025 and Internet Plus Manufacturing in China. Although each of these strategies was proposed under different circumstances, one of the common aims is to achieve smart manufacturing. However, without the intelligent system support, and without the support of data intelligent technology, “smart” cannot be achieved.

The objective of this Special Issue on “Intelligent Computing and System towards Smart Manufacturing” is to present the latest advances and developments of methods, techniques, systems, and tools dedicated to the applications of Intelligent Computing Science and technology toward smart manufacturing.

Subject Coverage

Topics include, but are not limited to, the following:

- Computational intelligence in smart manufacturing
- Deep learning for smart manufacturing
- Big data driven smart manufacturing system
- Data-driven smart factory and smart production
- Digital twin driven product design, manufacturing and service
- Smart manufacturing service
- CPS (Cyber-Physical Systems)-based manufacturing system
- Internet-of-Things based data collection
- Cloud-based design and manufacturing
- Data-driven robotic in smart factory
- Industrial big data mining algorithms
- Industrial application of big data technology
- Soft computing towards smart manufacturing

Important Date

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Manuscript submission

Submission of a manuscript implies: that the work described has not been published before. That it is not under consideration for publication anywhere else; that its publication has been approved by all co-authors, if any, as well as by the responsible authorities – tacitly or explicitly at the Institute where the work has been carried out. The Publisher will not be held legally responsible should there be any claims for compensation. Authors are encouraged to highlight the links of their work to the AIHC community, for example, by explicitly mentioning some previously published papers on the AIHC journal.

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Online Submission

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